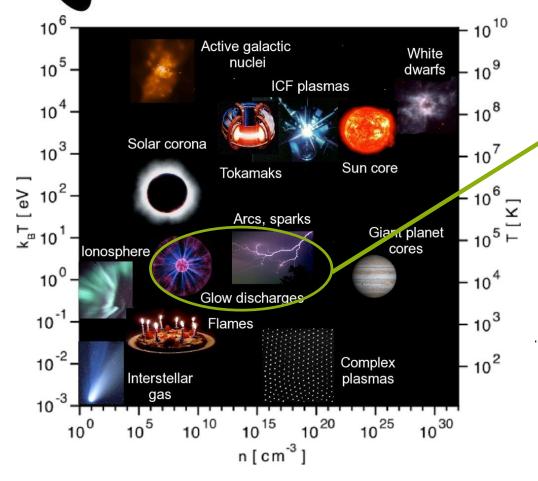




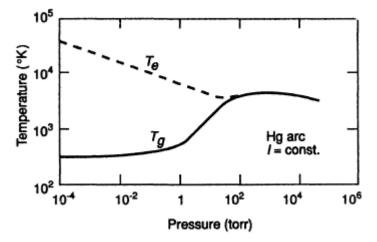
Physics Department, Faculty of Science
Tanta University



Low Temperature Plasma



- Low degree of ionization
- Neutral background 10⁶ the ion and electron density
 - Collisions with the background gas is dominant compared to electron ion collisions



Non-equilibrium plasmas at low pressures

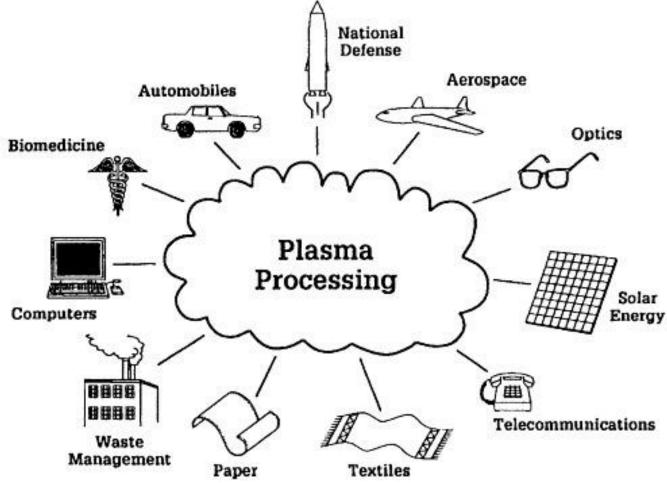
$$T_{\rm e} = 11000 - 60000 \rm K$$

$$T_{\rm e} = 1 - 5 {\rm eV}$$
 $T_{\rm i} = 300 {\rm K}$





Various applications

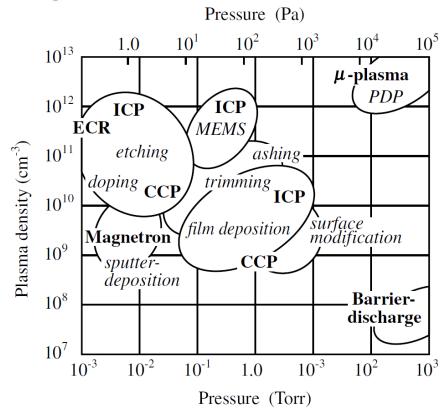






S

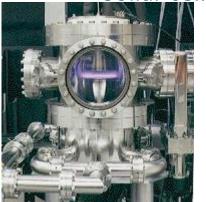
Devices

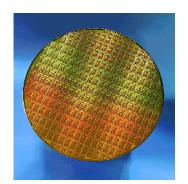


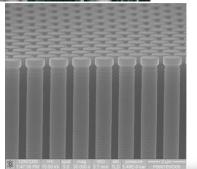
Plasma electronics,
Applications in Microelectronic Device Fabrication

- Capacitive coupled plasma are used in plasma etching and deposition process for production of:
 - Integrated circuits

Sollar cells



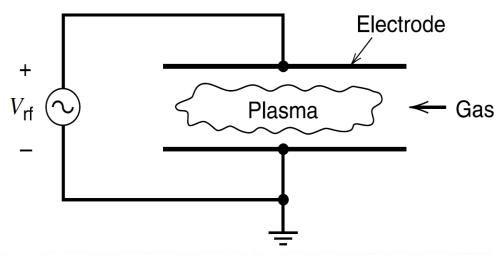


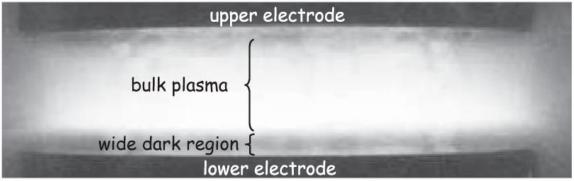






Symmetric CCP discharge



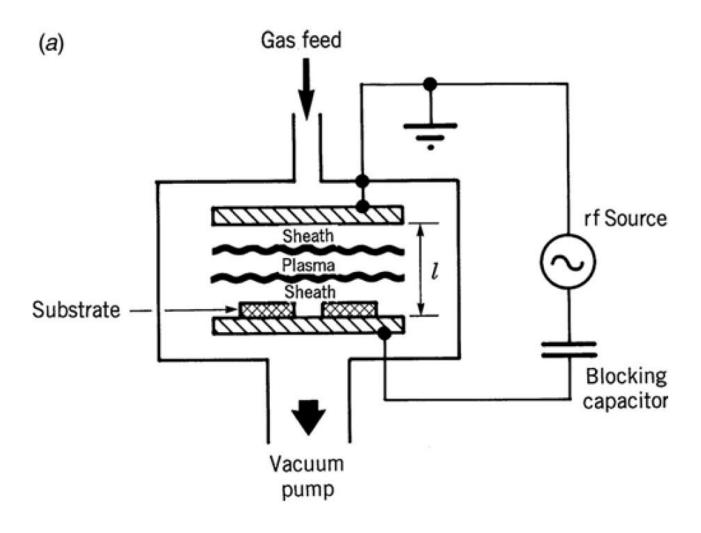


 The ion flux and the ion energies increase (decreases) by increasing (decreasing) the dreving frequency.





CCPs & blocking a Capacitor









Geometrically Asymmetric

- The RF current is constant.
- But the ground electroge

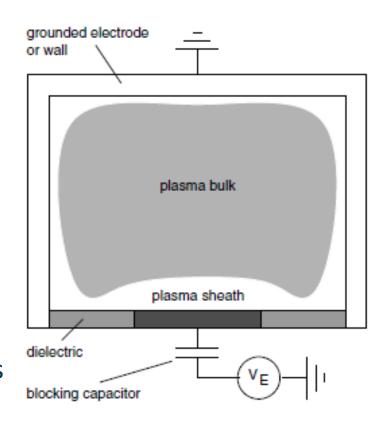
Area is greater then the powered electrode area.

$$J_{\rm g} = I_{\rm rf}/A_g$$
 $J_{\rm p} = I_{\rm rf}/A_p$

$$J_{\rm p} \gg J_{\rm g}$$

The blocking capacitor blocks DC currents:

$$\frac{V_{\rm p}}{V_{\rm g}} = (\frac{A_{\rm g}}{A_{\rm p}})^4$$



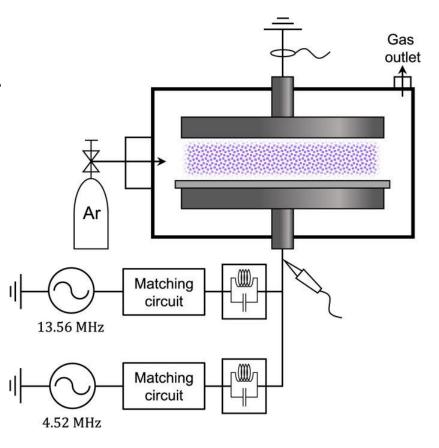






Electrically Asymmetric

- The high frequency controls the ion plasma bulk (ion flux).
- The lower frequency controls the plasma sheath.
- The phase shift between the two sources controls also the sheath potential.
- The independent control is not always perfect.

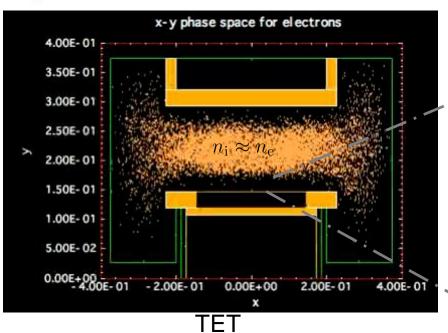


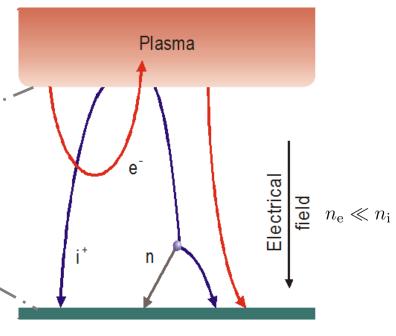






Plasma Sheaths





- RF sheaths:
 - High frequency regime
 - Intermediate frequency regime
 - Low frequency regime

$$\omega_{
m RF}\gg \omega_{
m pi}$$

$$n_{\rm i}(x) \Leftrightarrow \bar{E}(x)$$

$$\omega_{\mathrm{RF}} \approx \omega_{\mathrm{pi}}$$

$$\omega_{
m RF} \ll \omega_{
m pi}$$

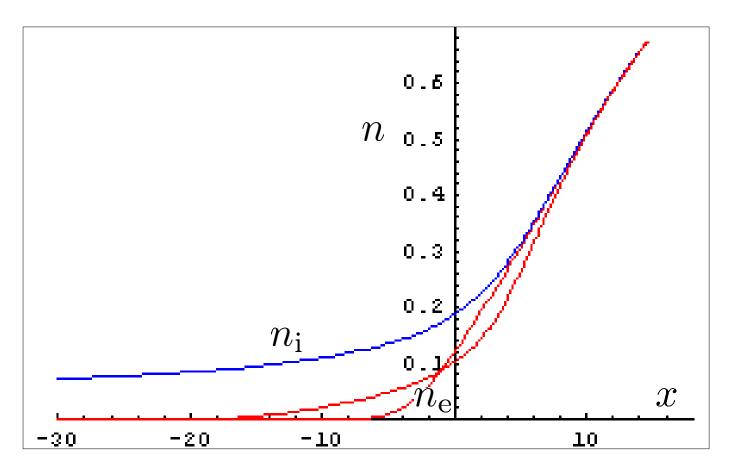
$$n_{\rm i}(x,t) \Leftrightarrow E(x,t)$$





Plasma Sheaths

$$\omega_{\mathrm{pe}} \gg \omega_{\mathrm{RF}} \gg \omega_{\mathrm{pi}}$$

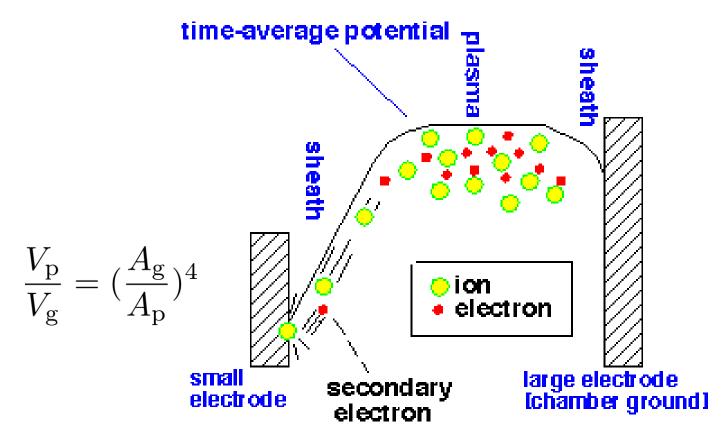








>> Particle and Potential distribution









Particle in Cell

Integration of equation of motion

$$F_i \to v_i \to x_i$$



Weighting

$$(E,B)_j \to F_i$$



Weighting

$$(x,v)_i \to (\rho,J)_j$$



Integration of field equation

$$(E,B)_i \leftarrow (\rho,J)_i$$



- Kinetically self-consistent and no constraints.
- Simulate the whole discharge.
- Follow the time evolution until the system is converged,
 i.e. the solution is periodic.







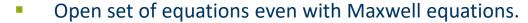
Fluid Models

- Transport =free flights + collisions
- Look from a distance at the ensemble of particles : transport coeffecients
- Fluid models: hydrodynamic transport

$$\frac{\partial \rho}{\partial t} + \vec{\nabla} \cdot (\rho \vec{u}) = S$$

$$\rho \left(\frac{\partial}{\partial t} + \vec{u} \cdot \vec{\nabla} \right) \vec{u} = qn(\vec{E} + \vec{u} \times \vec{B}) - \vec{\nabla} \cdot \Pi + \vec{S}_c$$

• • • • •



- Provide macroscopic description.
- Transport coeffecients are functions of local $\,(E/n)\,$ or on local mean free energy.

$$\frac{dE}{dx}\lambda \ll E \qquad \frac{dE}{dt}\nu^{-1} \ll E$$

Transport coeffecients can be derived from cross-sections, however, such calculations are
 zero-dimentional .





Plasma Chemistry I

Dissociation of feedstock gas into active neutral free radicals:

$$e^{-} + CF_{4} \rightarrow CF_{3} + F + e^{-}$$
 $e^{-} + CF_{4} \rightarrow CF_{2} + 2F + e^{-}$
 $e^{-} + CF_{4} \rightarrow CF_{+}F_{2} + F + e^{-}$

Dissociation of the free radicals

$$e^- + CF_3 \rightarrow CF_2 + F + e^-$$

 $e^- + CF_2 \rightarrow CF + F + e^-$







Plasma Chemistry II

Dissociative ionization and attachment:

$$e^{-} + CF_{4} \rightarrow CF_{3}^{+} + F + 2e^{-}$$
 $e^{-} + CF_{4} \rightarrow CF_{3}^{-} + F$
 $e^{-} + CF_{3} \rightarrow CF_{3} + F^{-}$

Chlorine discharge

$$e^{-} + Cl_{2} \rightarrow Cl_{2}^{+} + 2e^{-}$$
 $e^{-} + Cl_{2} \rightarrow Cl^{+} + Cl + 2e^{-}$







Plasma Chemistry III

Chemical reactions between neutrals in the presence of a third body

$$CF_3 + F + M \rightarrow CF_4 + M$$

 $CF_2 + F + M \rightarrow CF_3 + M$
 $CF + F + M \rightarrow CF_2 + M$

- At the substrate
- Removing

$$Cl(g) + Cl(ads) \rightarrow Cl_2(g)$$

Etching

$$Cl(g) + SiCl_3(s) \rightarrow SiCl_4(g) \uparrow$$

Deposition or growth

$$SiH(g) \rightarrow Si(s) \downarrow +H(g) \uparrow$$







Wet and Dry etching

- Carbon Floride (CF4) does not react with Silicin (Si).
- Dissociative ionization and attachment:

$$e^{-} + CF_{4} \rightarrow CF_{3}^{+} + F + 2e^{-}$$
 $e^{-} + CF_{4} \rightarrow CF_{3}^{-} + F$
 $e^{-} + CF_{3} \rightarrow CF_{3} + F^{-}$

Wet etching

$$\mathrm{Si}(s) + 4\mathrm{F}(g) \to \mathrm{SiF}_4(g) \uparrow$$

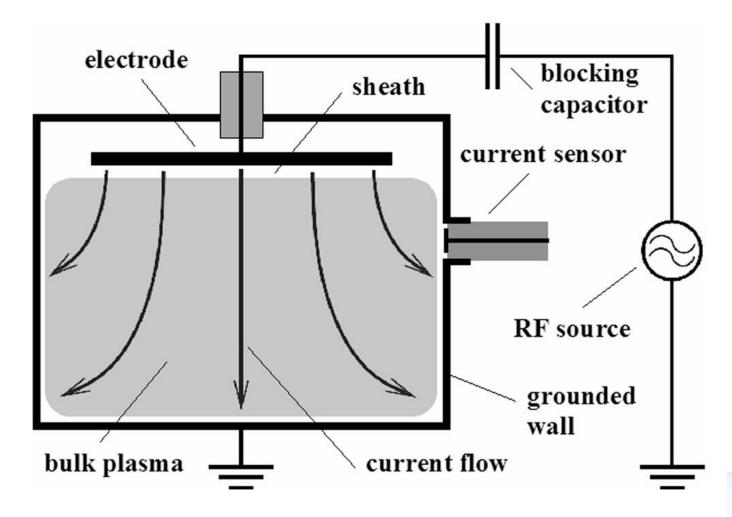
Dry etching: Accelerate CF₃⁺ toward the Silicon substrate







Why do we need an electrical model?

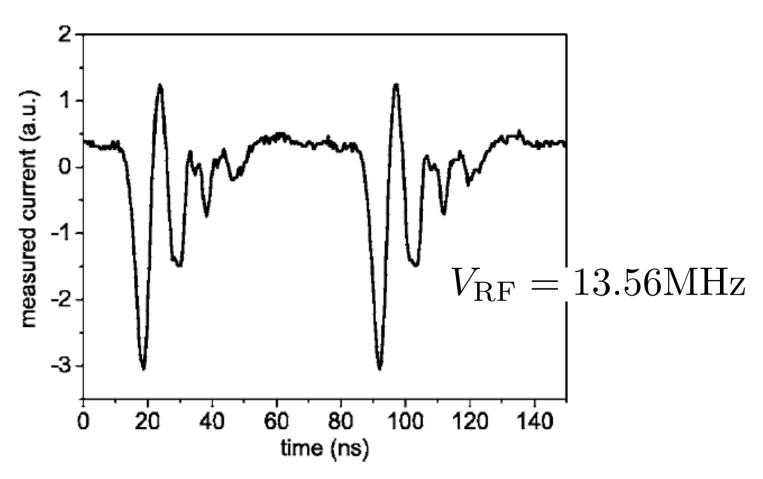








Measured Current



123503-2 Czarnetzki, Mussenbrock, and Brinkmann

Phys. Plasmas **13**, 123503 (2006)

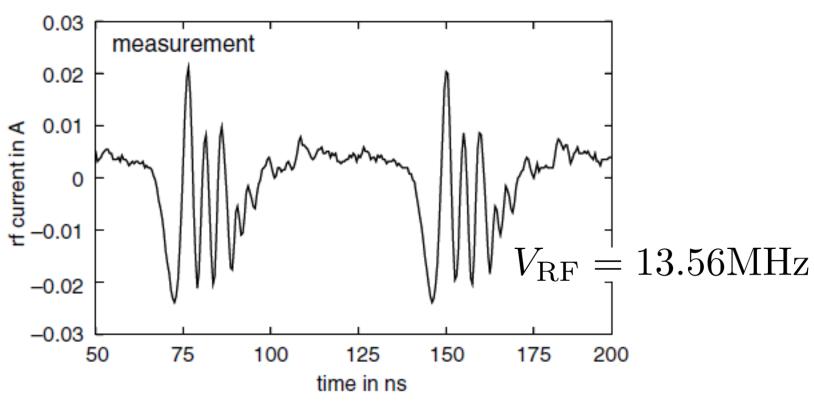


²¹E. Semmler and P. Awakowicz, private communication (2006).





Measured Current



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PLASMA SOURCES SCIENCE AND TECHNOLOGY

Plasma Sources Sci. Technol. 16 (2007) 377-385

doi:10.1088/0963-0252/16/2/022

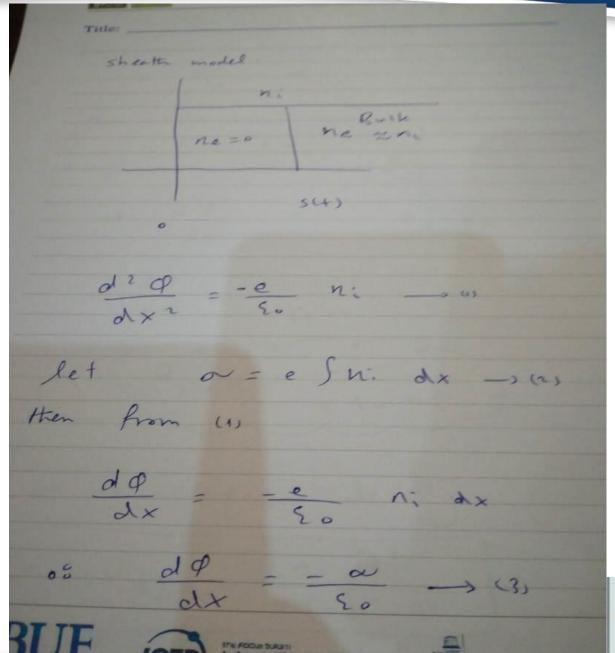


[14] Semmler E and Awakowicz P 2006 private communication





Sheath Model

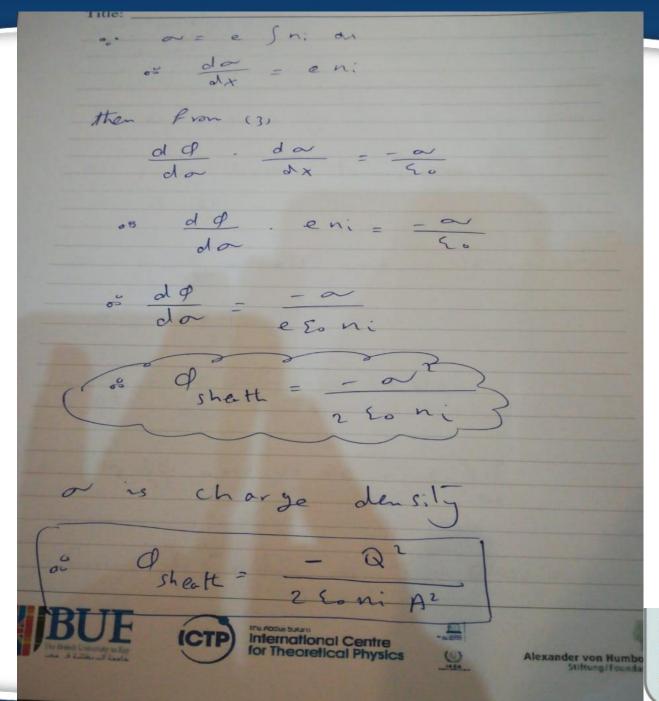






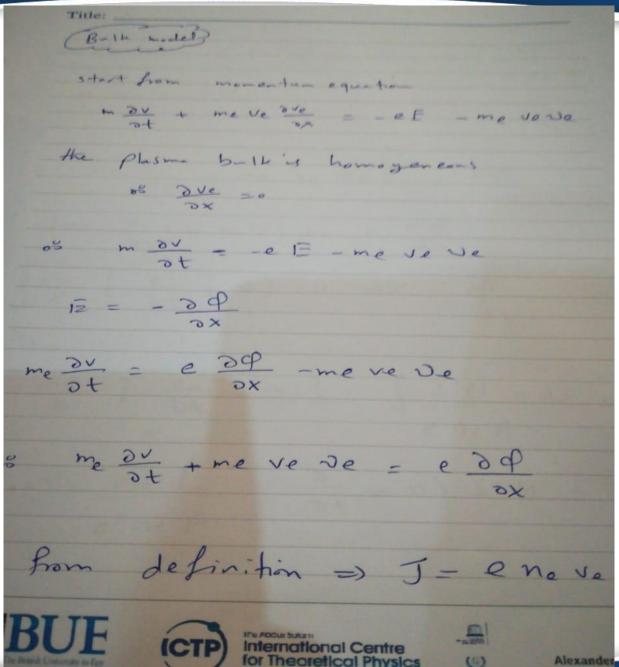


Sheath Model









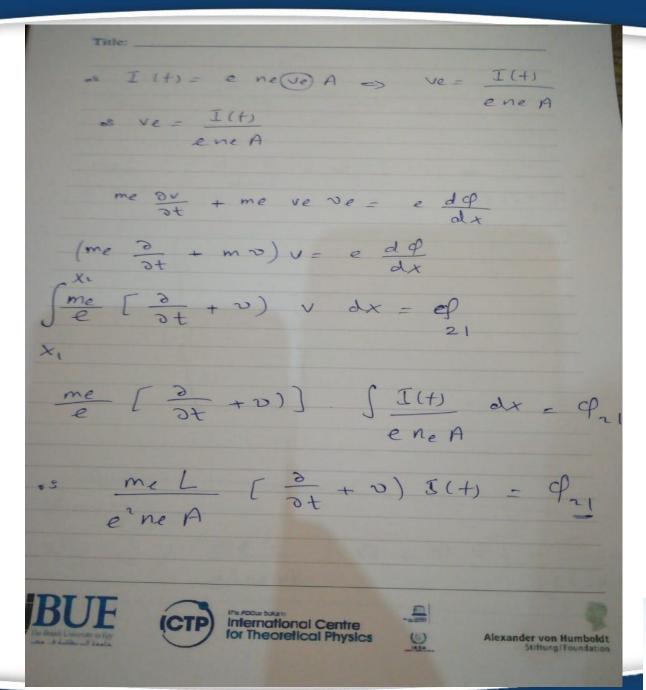








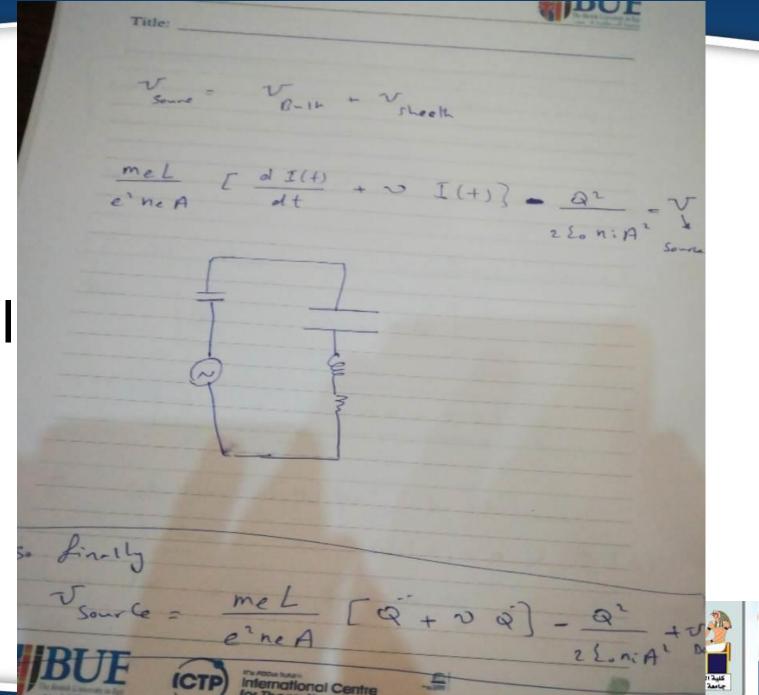






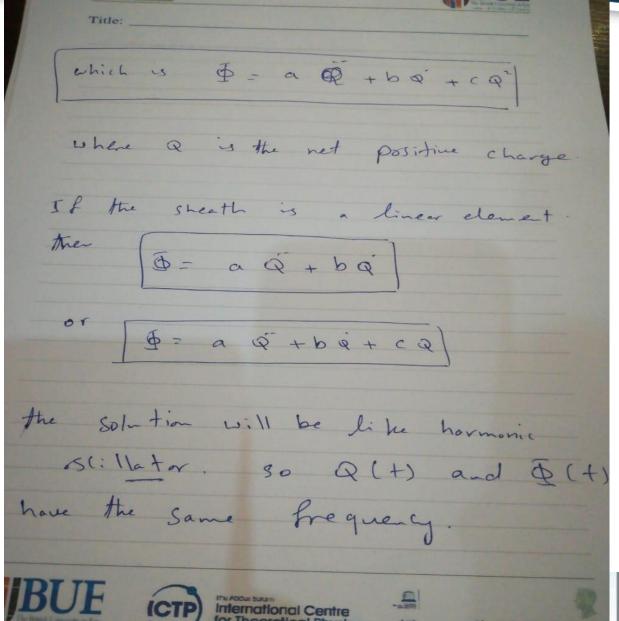
















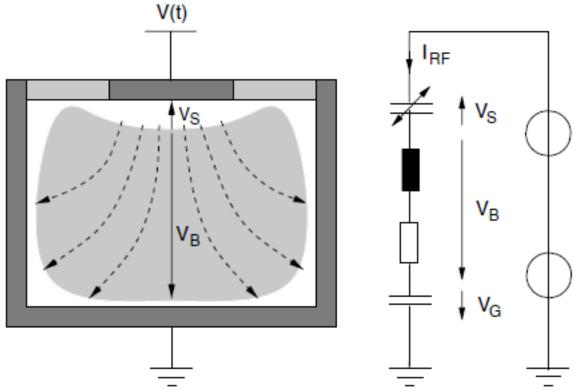


Alexander von Humboldt





2 RF discharge



Plasma Sources Sci. Technol. 17 (2008) 045011

D Ziegler et al

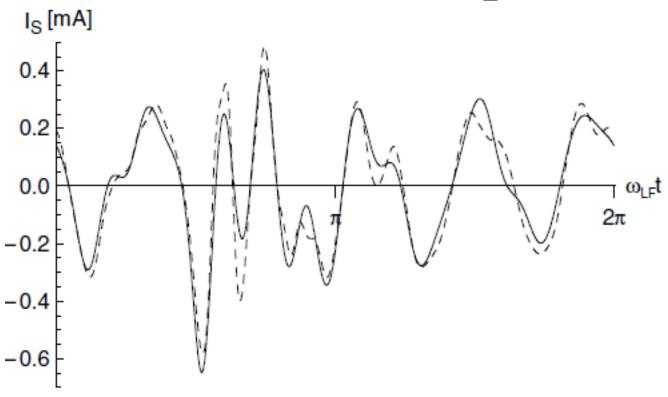
V(t)







2 RF discharge



Plasma Sources Sci. Technol. 17 (2008) 045011

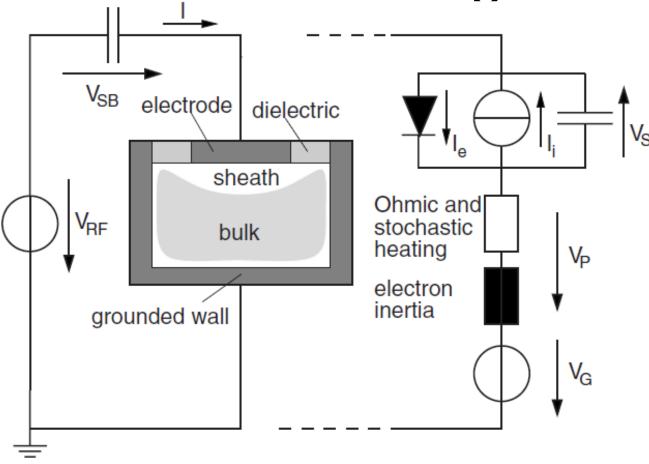
D Ziegler et al

$$L_{P} \frac{d^{2} Q}{dt^{2}} + \nu_{m} L_{P} \frac{d Q}{dt} + \sum_{k=2}^{M} V_{k} Q^{k} - V_{SB} - V_{G}$$
$$+ V_{LF} \cos(\omega_{LF} t + \phi_{LF}) + V_{HF} \cos(\omega_{HF} t + \phi_{HF}) = 0. \quad (31)$$





2 RF discharge



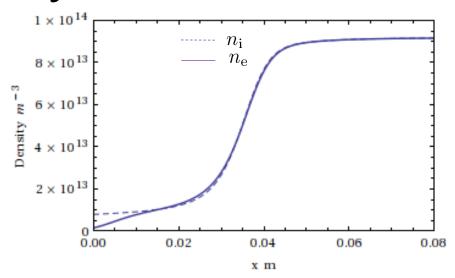
023503-2 Ziegler, Mussenbrock, and Brinkmann





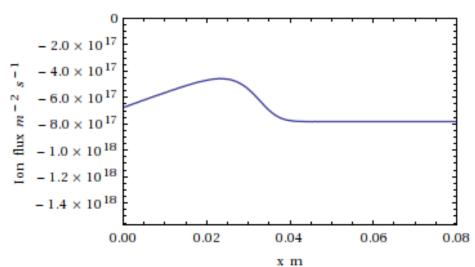


Ion Dynamics



The intermediate regime

$$\omega_{\mathrm{RF}} \approx \omega_{\mathrm{pi}}$$

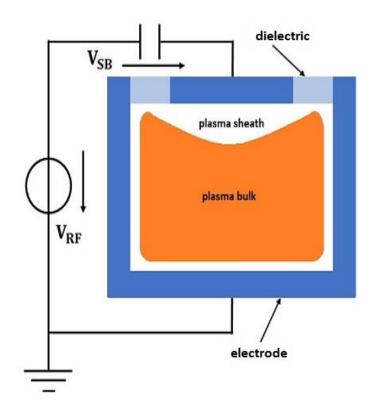




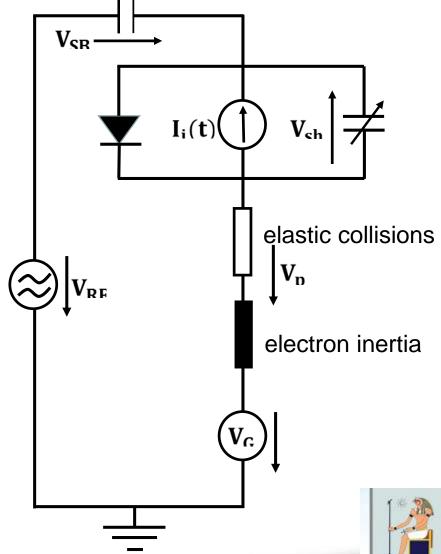




lumped model circuit of CCPs at the intermediate radiofrequencies









Model equations

$$\frac{dQ(t)}{dt} = -I - en_{\rm s}(t)A_{\rm s}u_{\rm s}(t) + en_{\rm B}\sqrt{(T_{\rm e}/2\pi m_{\rm e})}A_{\rm s}\exp(-eV_{\rm s}(t)/T_{\rm e})$$

$$V_{\rm s}(t) = \frac{Q^{2}(t)}{2\epsilon_{0}en_{\rm s}(t)A_{\rm s}^{2}}$$

$$\frac{m_{\rm e}L_{\rm B}}{e^{2}n_{\rm B}A_{\rm B}}\left(\frac{dI(t)}{dt} + \nu_{\rm eff}I(t)\right) = V_{\rm s}(t) - V_{\rm G} - V_{\rm SB}(t) + V_{\rm RF}(t)$$

$$V_{\rm G} = \frac{T_{\rm e}}{2e}\ln(\frac{m_{\rm i}}{2\pi m_{\rm e}})$$

$$C\frac{dV_{\rm SB}(t)}{dt} = I(t)$$

$$P(t) = \frac{m_{\rm e}L_{\rm B}}{e^{2}n_{\rm B}A_{\rm B}}\nu_{\rm eff}I^{2}(t) \qquad \bar{P}(t) = \frac{m_{\rm e}L_{\rm B}}{e^{2}n_{\rm B}A_{\rm B}\tau}\int_{0}^{t}\nu_{\rm eff}I^{2}(t)dt$$







Model equations

In order to include the ion dynamics in the RF sheath selfconsistently, the collisionless-sheath equations should be coupled to the system of equations:

$$\frac{\omega_{\rm RF}}{\omega_{\rm pi}} \frac{\partial n_{\rm s}}{\partial t} + \frac{\partial n_{\rm s} u_{\rm s}}{\partial s} = 0, \tag{12}$$

$$\frac{\omega_{\rm RF}}{\omega_{\rm pi}} \frac{\partial u_{\rm s}}{\partial t} + u_{\rm s} \frac{\partial u_{\rm s}}{\partial s} = -\frac{\partial V_{\rm s}(t)}{\partial s}.$$
 (13)

Assuming a first order perturbation approach, $n_s = \bar{n}_s + \delta n_s$, $u_s = \bar{u}_s + \delta u_s$, and $V_s = \bar{V}_s + \delta V_s$. Where \bar{n}_s , \bar{u}_s , \bar{V}_s are the time averaged ion density, ion speed, and sheath potential, respectively. While δn_s







$$n_{s}(t) = n_{B} + \delta n_{s}(t),$$

$$u_{s}(t) = u_{B} + \delta u_{s}(t).$$

The modulation of the ion density and the ion speed can be calculated approximately via

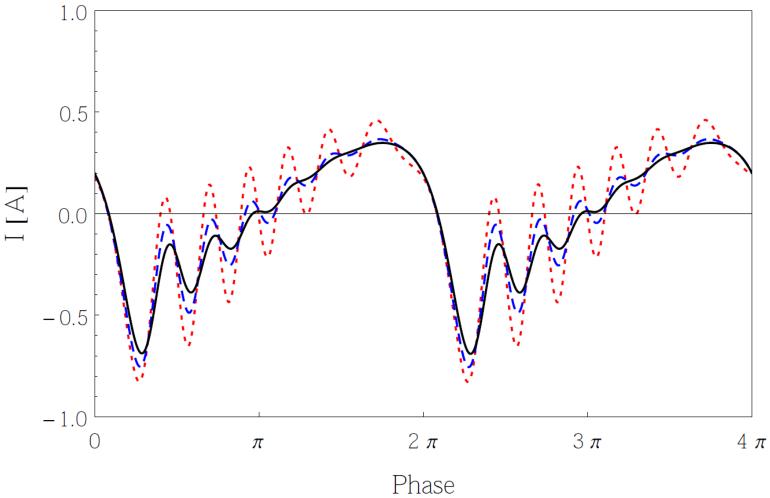
$$\frac{\omega_{\rm RF}}{\omega_{\rm pi}} \frac{\partial \delta n_{\rm s}}{\partial t} + \frac{\bar{u}_{\rm s} \delta n_{\rm s} + \bar{n}_{\rm s} \delta u_{\rm s}}{s} = 0, \tag{14}$$

$$\frac{\omega_{\rm RF}}{\omega_{\rm pi}} \frac{\partial \delta u_{\rm s}}{\partial t} + \frac{\bar{u}_{\rm s} \delta u_{\rm s} + \delta V_{\rm s}}{s} = 0, \tag{15}$$









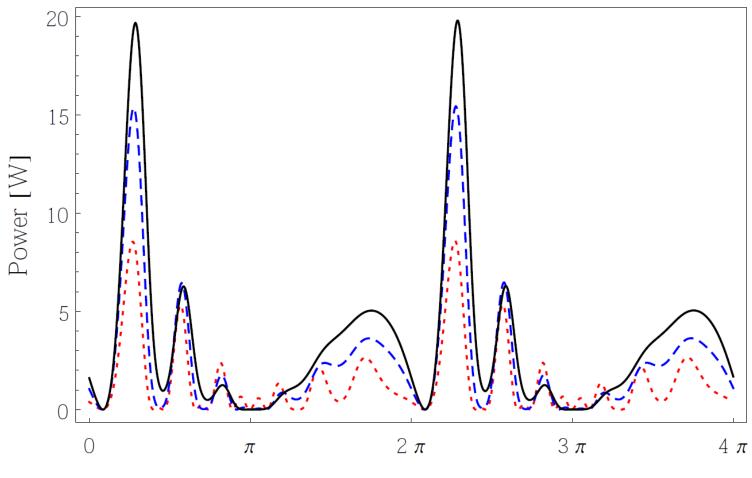
■50 mTorr Black, 30 mTorr Blue, 10 mTorr Red

13.56 MHz









Phase

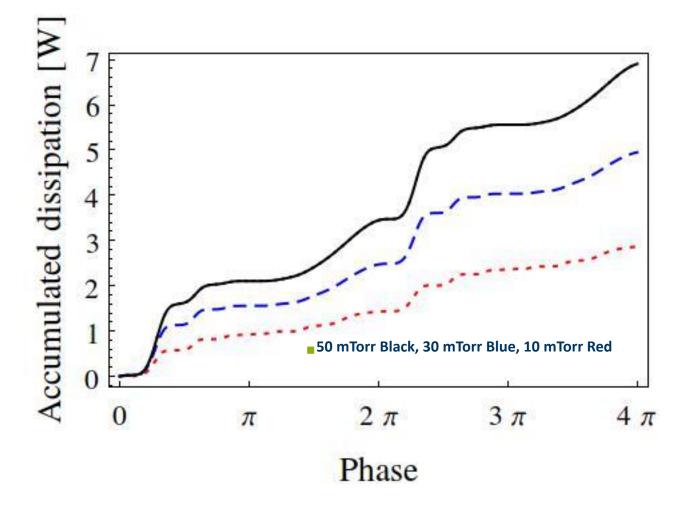
■50 mTorr Black, 30 mTorr Blue, 10 mTorr Red

■13.56 MHz









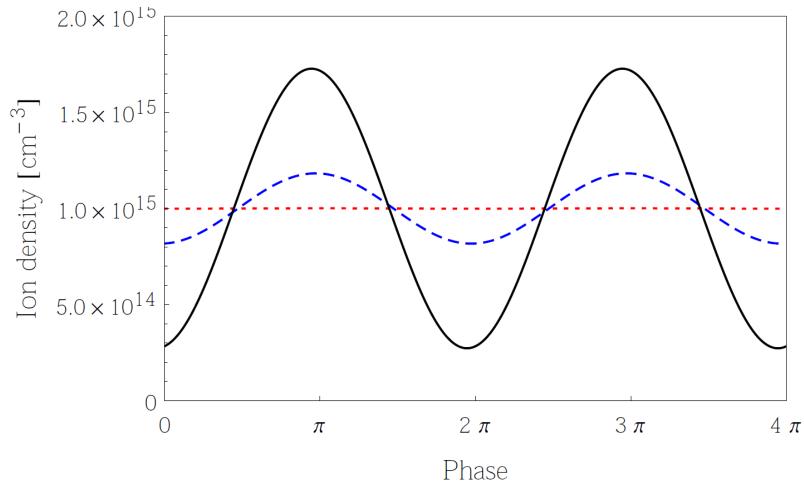
■50 mTorr Black, 30 mTorr Blue, 10 mTorr Red

13.56 MHz







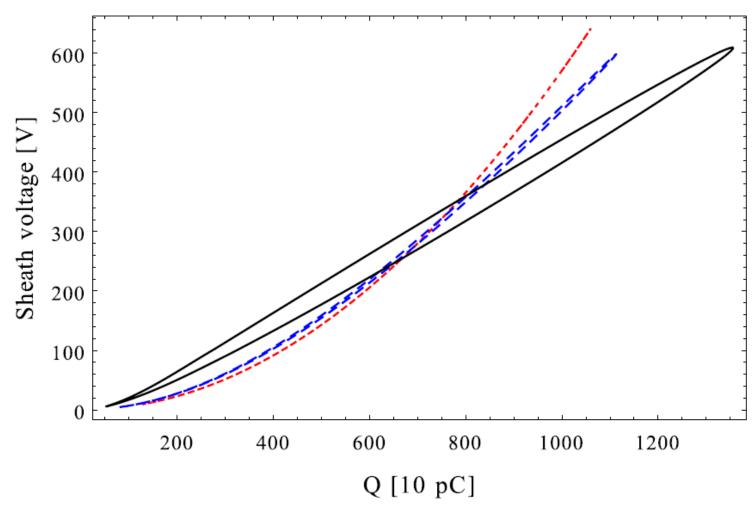




■13.56 MHz dotted, 1MHz dashed, 0.5 MHz solid







■13.56 MHz dotted, 1MHz dashed, 0.5 MHz solid







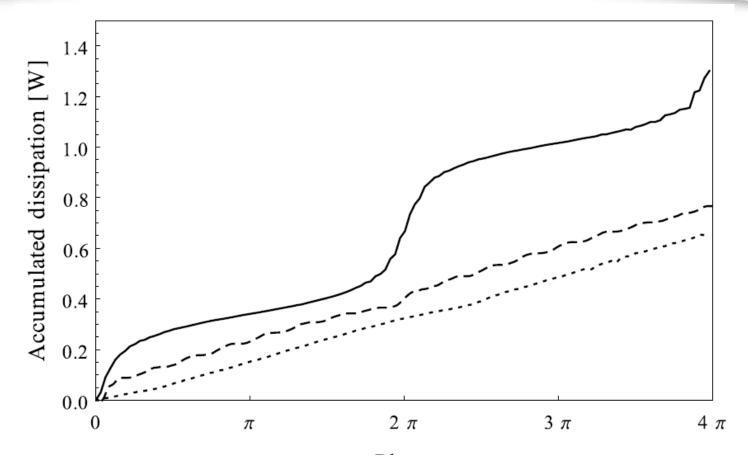


Fig. 8. The phase-accumulated power when $V_{RF} = 300[\cos(0.5 \text{ MHz } t + \theta) + \cos(13.56 \text{ MHz } t)]$ V. Dashed-black, dotted-black represent the cases $\theta = 0$ and $\theta = -\pi/2$, respectively. The solid-black line represents the results when the ion modulation is ignored and $\theta = 0$.







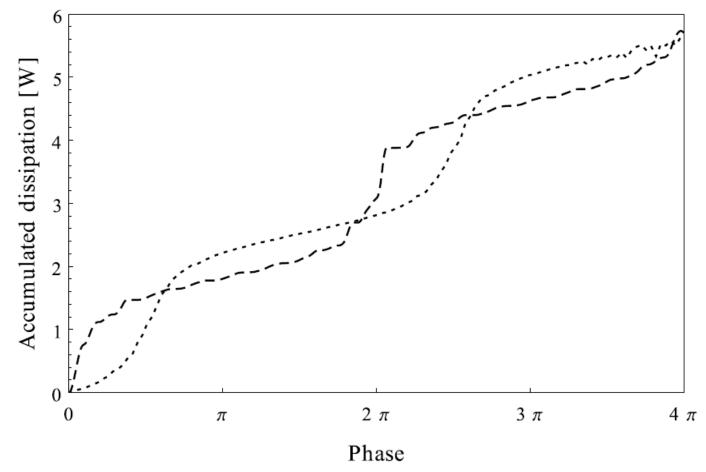


Fig. 9. The phase-accumulated power when $V_{RF} = 300[\cos(1 \text{ MHz } t + \theta) + \cos(13.56 \text{ MHz } t)]$ V. Dashed-black, dotted-black represent the cases $\theta = 0$ and $\theta = -\pi/2$, respectively.





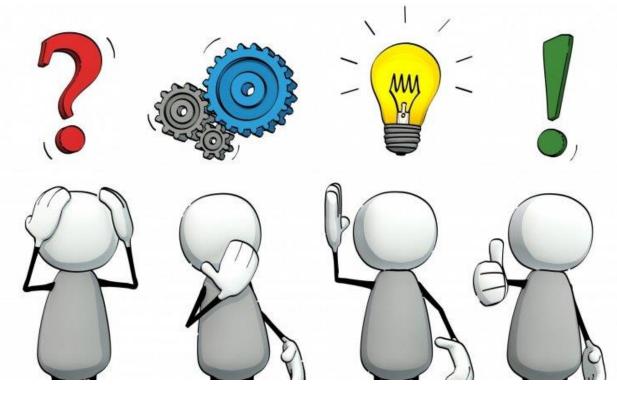
Open Discussion

Can the ion modulation heat the plasma?









Thanks!



